

REMARKS

Claims 45-49 are pending. Applicants respectfully request reconsideration of the application.

Claims 45-49 stand rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,685,951 ("Torek"). Applicants respectfully traverse the rejection.

Claim 45 recites a semiconductor device comprising, in part, "an opening in said insulating layer, said opening having sidewalls and a bottom, said bottom being substantially free of polymer residue and silicon rich oxide residue; and a conductor in said opening."

The Office Action contends that Torek teaches all of the limitations of claim 45. Particularly, the limitation "said bottom being substantially free of polymer residue and silicon rich oxide residue." (Office Action, p.2). The cited portions of the reference, however, only disclose that a vapor phase etch cleaning may be employed to remove native oxide and other oxide contamination at contact area 28. (Torek, col. 5, lines 17-20). Thus, Torek does not disclose, teach or suggest a "bottom being substantially free of polymer residue and silicon rich oxide residue." Therefore, Applicants respectfully request the rejection of claim 45 should be withdrawn and the claim allowed.

Claim 46 recites an integrated circuit comprising, in part, "an ammonia-cleaned High Aspect Ratio opening provided in an insulating layer, said opening being formed over a polysilicon region and a bottom of said opening being substantially free of polymer residue and silicon rich oxide residue; and a conductor within said opening, said conductor being electrically connected with said polysilicon region." Torek does not teach all of the limitations of claim 46.

As set forth above, Torek only discloses that a vapor phase etch cleaning may be employed to remove native oxide and other oxide contamination. Torek does not disclose, teach or suggest a "bottom being substantially free of polymer residue and silicon rich oxide residue." For at least this reason, the rejection of claim 46 and dependent claims 47-49 should be withdrawn and the claims allowed.

Reconsideration is respectfully solicited.

Dated: November 21, 2006

Respectfully submitted,

By 

Thomas J. D'Amico

Registration No.: 28,371
DICKSTEIN SHAPIRO LLP
1825 Eye Street, NW
Washington, DC 20006-5403
(202) 420-2200
Attorney for Applicant